

RESIN COMPOSITION, CURED FILM, LAMINATED FILM, AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

Abstract

To provide: a highly heat-resistant resin composition which exhibits good adhesiveness at low temperatures of 180°C or less, while being free from the generation of a volatile content due to decomposition or the like even at high temperatures of 250°C or more, and which can be easily separated at room temperature during separation of the base since increase in the adhesive power is small even after a heat treatment step; and a cured film and a laminated film, each of which uses this resin composition. [Solution] A resin composition which contains a polyimide resin and a methylol compound, and which is characterized in that the polyimide resin has an acid dianhydride residue and diamine residues and that at least a residue of a polysiloxane diamine represented by general formula (1) and a residue of an aromatic diamine having a hydroxyl group are contained as the diamine residues; and a cured product and a laminated film, each of which uses this resin composition. (In the formula, n is a natural number which has an average value within the range of 5-30 as calculated from the average molecular weight of the polysiloxane diamine; R1 and R2 may be the same as or different from each other, and each represents an alkylene group having 1-30 carbon atoms or a phenylene group; and R3-R6 may be the same as or different from each other, and each represents an alkyl group having 1-30 carbon atoms, a phenyl group or a phenoxy group.)

